

ABSTRACT OF THE DISCLOSURE

A component mounting method for mounting several micro component chips aligned in parallel onto a board by soldering. An allowable offset is set for each
5 electrode, taking into account a self-alignment effect of melted solder in soldering for bonding component terminals onto electrodes formed on the board corresponding to a component layout. Solder printing and component placement onto the electrodes are shifted by the offset. This offset is balanced by the self-alignment effect of melted solder, and each component is secured at an appropriate position. This
10 mounting method allows less stringent spacing conditions to be applied for mounting and prevents the occurrence of defects during printing and placement.